PCN Number:		20171205002				PCN Date:	December 06, 2017				
Title:	Datasheet for	LMX2	582								
Custome	r Contact:	PCN N	<u> 1anage</u>	er			D	ept:	Quality Services		
Change 1	Гуре:										
	Assembly Site			Design			Wafer Bump Site				
Assembly Process			\boxtimes	2444 0000			_	Wafer Bump Material			
Assembly Materials					Part number change				Wafer Bump Process		
Mechanical Specification					Test Site			-	Nafer Fab Site		
Packing/Shipping/Labeli			ig		Test Process				Wafer Fab Materials Wafer Fab Process		
			Notification Dotails					JVa	ITER Fab Process		
Notification Details Description of Change:											
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details. LMX2582 SNAS680D - DECEMBER 2015-REVISED NOVEMBER 2017											
Changes from Revision C (July 2017) to Revision D Page • Switched the RFoutBP and RFoutBM pins in the pinout diagram											
The datasheet number will be changing.											
Device Family			Change From:					Change To:			
LMX258	LMX2582				SNAS680C			SNAS680D			
These changes may be reviewed at the datasheet links provided.											
http://www.ti.com/product/LMX2582											
Reason for Change:											
To accurately reflect device characteristics.											
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes											
to the actual device. Changes to product identification resulting from this PCN:											
None.											
Product Affected:											
LMX2582		IMX	2582R	HΔ	т						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com